SPECIFICATION AMENDMENTS

Please replace the second full paragraph on page 12 of the specification with the following paragraph:

Fig. 8 shows the state where bumps 12 are shaped into a hemispherical shape by supplying the solder paste to the lands and the state where the planar surface 12a is formed on the top of each bump 12 by coining. In the drawing, H_o represents the height of the bump 12 before coining ~~coiling~~, and h_0 represents the height of the bump 12 after coining. When the radius of the planar surface 12a is r_o by approximating the planar surface 12a to a circle, the height h_o after coining of the bump 12 can be approximating to $h_o = H_o - r_o$. In other words, $H_o = h_o + r_o$. Here, the height h_o of the bump 12 after coining is the value that is set in advance by a processing machine. Assuming that H_o is the design value (standard value) of the height of the bump 12, the standard radius r_o of the planar surface 12a is determined for the bumps 12 having the standard size when h_o is set. When the planar surface 12a of a certain bump 12 is measured and its radius r proves the standard radius r_o, on the contrary, it can be understood that the bump 12 is shaped into the standard (design) size.
